

Hermetic Circular DC Connectors

Overview

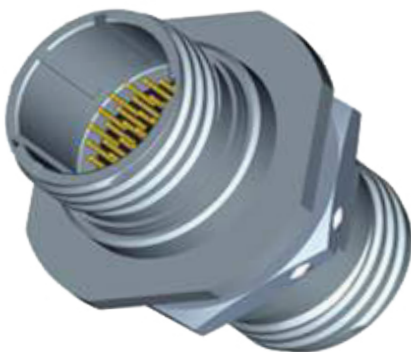
PA&E, A Qnnect company, combines ceramic-to-metal sealing technology with light-weight materials to create reliable hermetic MIL-DTL-38999 compliant connectors that are up to 60% lighter than stainless steel versions. This technology is proven in the harshest environments – from deep beneath the earth's surface to deep space and even within the human body. Our 38999 style connector provide a unique solution for applications that require a combination of light weight, and high electrical performance.



Technical Specifications

Materials

- Material Compatibility: Designed for Al, Ti or Iron/Nickel Alloy Applications
- Shell Finish Options: Passivated, Nickel/Gold Plated or Chromate Conversion Coated as Applicable
- Contact Material: Beryllium Copper CDA Alloy 172/173
- Contact Finish: Nickel/Gold Plating



Electrical

- Current Rating: Subject to Pin Configuration
- Insulation Resistance: Provides Greater than 5,000 Megohms at 500 VDC When Tested in IAW MIL-STD- 1344, Method 3003
- Dielectric Withstanding Voltage: Exhibits No Evidence of Breakdown or Flash-over When Tested in IAW MIL-STD-1344, Method 3003

Environmental

- Operating Temperature: -65°C to 200°C
- Salt Spray Resistance: Connectors Meet Salt Spray Test in IAW MIL-STD-1344, Method 3003
- Sealing: Kryoflex Polycrystalline Ceramic

Mechanical

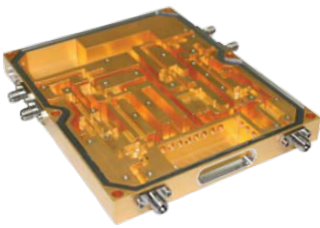
- Interface: Per MIL-DTL-38999
- Number of Contacts: Per MIL DTL-38999
- Leak Rate: Less Than 1×10^{-9} cc/sec helium at 1 Atmospheric Differential Pressure



For More Info:
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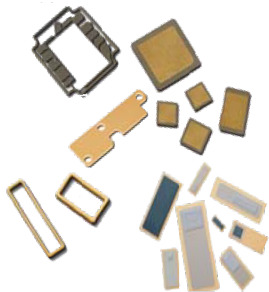


Other Products & Services



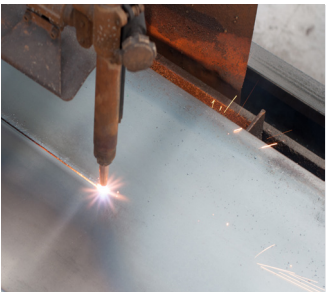
Hermetic Electronic Packaging

We bring customers' hermetic electronic package designs to life and use unique materials and manufacturing processes to help optimize for weight savings, footprint reduction, thermal transfer and more. Our precision machining capabilities allow us to meet very tight tolerances for aluminum and titanium housings. We deliver the custom packaging solutions that ensure the electronics within those devices are unaffected by whatever extreme environmental condition they operate in.



Enabling Components

There's more to a reliable hermetic package solution than a box and connectors and we manufacture components to ensure a module's long term viability. We produce: getters to prevent build-up of contaminants; solder preforms that aid in attaching electronic circuitry; ring frames that become integral side walls of a hermetic package; and custom thermal spreaders that ensure heat from a chip or substrate is efficiently dissipated. To top things off, we also manufacture package lids.



Laser and Integration Services

We provide high-speed laser welding, sealing and marking with consistent accuracy. Our laser welding expertise also extends to the manufacture of custom designed/build laser welding, cutting & sealing systems for customers who wish to bring those capabilities in house.